nexperia

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023 Based on structural similarity

| Supplier | | User Part Number | | | | |
|--|--|--|-------------|-----------|------------|-----------|
| Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test | | BZT52H-C15-Q Part Description | | | | |
| | | | | | | |
| | | SMD package | | | | |
| | | Test Conditions | Duration | # Lots | # Quantity | # Rejects |
| | | | TEST | | | |
| | Pre- and Post-Stress | | | | | |
| # E1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below |
| | | JESD22-A113 | | | | |
| | | Bake Tamb = 125 °C | 24 hours | | | |
| | PC | Soak Tamb = 85 °C, RH = 85% | 168 hours | | <i></i> | |
| # A1 | Preconditioning | Reflow soldering | 3 cycles | 1514 | 64430 | 0 |
| | | MIL-STD-750-1 | | | | |
| | HTRB | M1038 Method A Tj = Tjmax, VR = 80 % of rated reverse | | | | |
| # B1 | Bias | voltage | 1000 hours | 250 | 11400 | 0 |
| # DI | Dias | MIL-STD-750-1 | 1000 110015 | 230 | 11400 | 0 |
| | | MIL-STD-750-1 M1038 Method B | | | | |
| | SSOP | $T_j = T_j max$, $I_z = 100\%$ of max. datasheet | | | | |
| # B1b | Steady State Operational | reverse current | 1000 hours | 44 | 1920 | 0 |
| | · · · · · · · · · · · · · · · · · · · | | | | | |
| | тс | JESD22-A104 | | | | |
| # A4 | Temperature Cycling | -65 °C to Tjmax, not to exceed 150°C | 1000 cycles | 311 | 14080 | 0 |
| | | | | | | |
| | UHAST | JESD22-A118 | | | | |
| # A3 or | Unbiased HAST | Tamb = 130 °C, RH = 85 % | 96 hours | 311 | 14080 | 0 |
| | | JESD22-A102 | | | | |
| | AC | Tamb = 121 °C, RH = 100 % | | | | |
| # A3 alt | Autoclave | Pressure = 205 kPa (29.7 psia) | | | | |
| | | | | | | |
| | H3TRB | JESD22-A101 | | | | |
| # 42 alt | High Humidity High Temperature Reverse Bias | Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^[1] | 1000 hours | 211 | 14090 | 0 |
| # A2 alt | remperature Reverse Blas | | 1000 hours | 311 | 14080 | 0 |
| | IOL | MIL-STD-750 Method 1037 | | | | |
| # A5 | Intermittent Operating Life | ton = toff, devices powered to insure ΔT_j = 100 °C for 15000 cycles | 1000 hours | 312 | 14120 | 0 |
| # A3 | Internittent Operating Life | | 1000 Hours | 512 | 14120 | U |
| | RSH | JESD22-A111 | | | | |
| # C8 | Resistance to Solder Heat | $260 \text{ °C} \pm 5 \text{ °C}$ | 10 s | 269 | 8070 | 0 |
| | SD | | 200 | 205 | 2070 | <u> </u> |
| # C10 | Solderability | J-STD-002 | | 19 | 6660 | 0 |
| | | | | | | - |

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| (FIT) MTTF (hrs) |
|------------------|
| |
| 2,68E+09 |
| |

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